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Full Material Declaration for attached parts list

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Declarations authorised by:
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Declaration effective from: 1 January 2016 [Approved on 9 April 2021, 09:22 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.53%	Gold	7440-57-5	12.5%
			Polydimethyl siloxane	63148-62-9	25%
			Silicon	7440-21-3	62.5%
Die attach	Lead and Lead alloys	0.04%	Silver	7440-22-4	1.5%
			Tin	7440-31-5	3%
			Lead	7439-92-1	95.5%
Encapsulation	EP (Epoxy resin)	26.14%	Carbon black	1333-86-4	0.3%
			ANTIMONY TRIOXIDE	1309-64-4	0.8%
			TBBA	98-73-7	0.99%
			Epoxy resin 89	26335-32-0	27.61%
			Quartz sand	60676-86-0	70.3%
Leadfinish	Tin plating	2.56%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	70.73%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
D 2.5x10	Diode Axial	0.5	g

No need to provide safe use information beyond the identification of the Candidate List substance